RGW00TS65DHR

650V 50A Field Stop Trench IGBT

Datasheet

V _{CES}	650V
I _{C (100°C)}	50A
V _{CE(sat) (Typ.)}	1.5V
P_{D}	254W

Outline TO-247N (1) (2)(3)

Features

- 1) AEC-Q101 Qualified
- 2) Low Collector Emitter Saturation Voltage
- 3) Low Switching Loss & Soft Switching
- 4) Built in Very Fast & Soft Recovery FRD
- 5) Pb free Lead Plating; RoHS Compliant

Application

Automotive

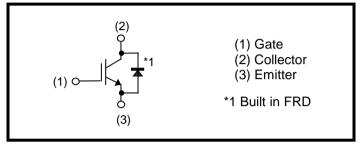
On & Off Board Chargers

DC-DC Converters

PFC

Industrial Inverter

●Inner Circuit



Packaging Specifications

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	Packaging	Tube			
Type B	Reel Size (mm)	-			
	Tape Width (mm)	-			
	Basic Ordering Unit (pcs)	450			
	Packing Code	C11			
	Marking	RGW00TS65D			

● Absolute Maximum Ratings (at T_C = 25°C unless otherwise specified)

Parameter		Symbol	Value	Unit
Collector - Emitter Voltage		V _{CES}	650	V
Gate - Emitter Voltage		V_{GES}	±30	V
Collector Current	T _C = 25°C	I _C	96	А
Collector Current	T _C = 100°C	I _C	58	А
Pulsed Collector Current		I _{CP} *1	200	А
Diode Forward Current	T _C = 25°C	I _F	56	А
	T _C = 100°C	I _F	33	А
Diode Pulsed Forward Current		I _{FP} *1	200	А
Dower Dissipation	T _C = 25°C	P _D	254	W
Power Dissipation	T _C = 100°C	P _D	127	W
Operating Junction Temperature		T _j	-40 to +175	°C
Storage Temperature		T _{stg}	-55 to +175	°C

^{*1} Pulse width limited by T_{jmax.}

●Thermal Resistance

Parameter	Cumbal	Values			Unit
Farameter	Symbol	Min.	Тур.	Max.	Offic
Thermal Resistance IGBT Junction - Case	$R_{\theta(j-c)}$	-	ı	0.59	°C/W
Thermal Resistance Diode Junction - Case	$R_{\theta(j-c)}$	-	ı	1.17	°C/W

●IGBT Electrical Characteristics (at T_j = 25°C unless otherwise specified)

Parameter	Symbol	Conditions	Values			Unit
r arameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Collector - Emitter Breakdown Voltage	BV _{CES}	$I_{C} = 10 \mu A, V_{GE} = 0 V$	650	ı	ı	V
Collector Cut - off Current	I _{CES}	$V_{CE} = 650V, V_{GE} = 0V$	-	-	10	μΑ
Gate - Emitter Leakage Current	I _{GES}	$V_{GE} = \pm 30V, V_{CE} = 0V$	-	-	±200	nA
Gate - Emitter Threshold Voltage	$V_{GE(th)}$	$V_{CE} = 5V, I_{C} = 33.0 \text{mA}$	5.0	6.0	7.0	V
Collector - Emitter Saturation Voltage	V _{CE(sat)}	$I_{C} = 50A, V_{GE} = 15V,$ $T_{j} = 25^{\circ}C$ $T_{j} = 175^{\circ}C$	-	1.5 1.85	1.9 -	V

●IGBT Electrical Characteristics (at T_j = 25°C unless otherwise specified)

Parameter	Symbol	Conditions	Values			Unit
Parameter			Min.	Тур.	Max.	Offic
Input Capacitance	C _{ies}	$V_{CE} = 30V$,	-	4200	-	-
Output Capacitance	C _{oes}	$V_{GE} = 0V$,	-	104	-	рF
Reverse transfer Capacitance	C _{res}	f = 1MHz	-	79	-	
Total Gate Charge	Q_g	V _{CE} = 400V,	-	141	-	
Gate - Emitter Charge	Q_ge	$I_{\rm C} = 50A$,	-	30	-	nC
Gate - Collector Charge	Q_{gc}	V _{GE} = 15V	-	52	-	
Turn - on Delay Time	t _{d(on)}		-	48	-	
Rise Time	t _r	$I_C = 25A, V_{CC} = 400V,$ $V_{GE} = 15V, R_G = 10\Omega,$	-	13	-	ns
Turn - off Delay Time	t _{d(off)}	$T_i = 25^{\circ}C$	-	186	-	
Fall Time	t _f	Inductive Load *E _{on} include diode reverse recovery	-	37	-	
Turn - on Switching Loss	E _{on}		-	0.43	-	mJ
Turn - off Switching Loss	E _{off}		-	0.44	-	
Turn - on Delay Time	t _{d(on)}		-	45	-	
Rise Time	t _r	$I_C = 25A, V_{CC} = 400V,$ $V_{GF} = 15V, R_G = 10\Omega,$	-	15	-	ns
Turn - off Delay Time	t _{d(off)}	$T_i = 175^{\circ}C$	-	218	-	
Fall Time	t _f	Inductive Load	-	76	-	
Turn - on Switching Loss	E _{on}	*E _{on} include diode reverse recovery	-	0.44	-	m l
Turn - off Switching Loss	E_{off}		-	0.63	-	mJ
Reverse Bias Safe Operating Area	RBSOA	$I_C = 200A$, $V_{CC} = 520V$, $V_P = 650V$, $V_{GE} = 15V$, $R_G = 100\Omega$, $T_j = 175^{\circ}C$	FU	LL SQUA	.RE	-

●FRD Electrical Characteristics (at T_j = 25°C unless otherwise specified)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Тур.	Max.	Offic
	I _F = 30A,	I _F = 30A,				
Diode Forward Voltage	V_{F}	T _j = 25°C	-	1.45	1.9	V
		T _j = 175°C	-	1.55	-	
Diode Reverse Recovery Time	t _{rr}	$I_F = 25A$, $V_{CC} = 400V$, $di_F/dt = 200A/\mu s$, $T_j = 25^{\circ}C$	-	90	-	ns
Diode Peak Reverse Recovery Current	I _{rr}		-	7.9	1	А
Diode Reverse Recovery Charge	Q _{rr}		-	0.39	1	μC
Diode Reverse Recovery Energy	E _{rr}		-	19.0	-	μJ
Diode Reverse Recovery Time	t _{rr}	$I_F = 25A,$ $V_{CC} = 400V,$ $di_F/dt = 200A/\mu s,$ $T_j = 175^{\circ}C$	-	161	-	ns
Diode Peak Reverse Recovery Current	I _{rr}		-	10.8	-	А
Diode Reverse Recovery Charge	Q _{rr}		_	1.03	-	μC
Diode Reverse Recovery Energy	E _{rr}		-	73.1	-	μJ

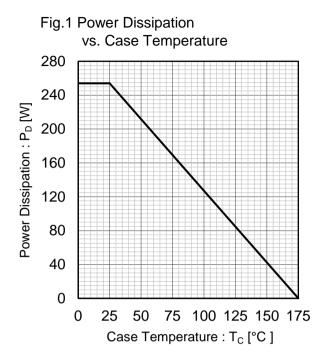


Fig.2 Collector Current vs. Case Temperature 110 100 90 Collector Current : Ic [A] 80 70 60 50 40 30 20 T_j ≤ 175°C 10 _{GE} ≥ 15V 25 50 75 100 125 150 175 Case Temperature : T_C [°C]

Fig.3 Forward Bias Safe Operating Area

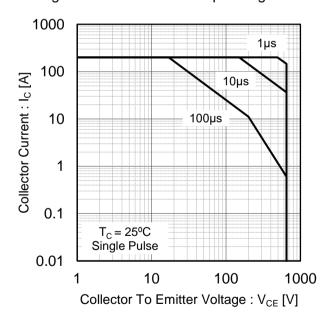


Fig.4 Reverse Bias Safe Operating Area

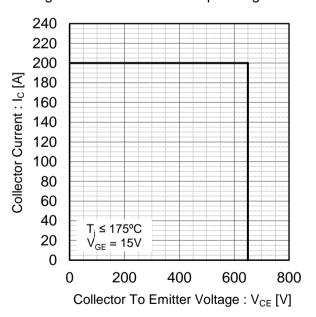


Fig.5 Typical Output Characteristics

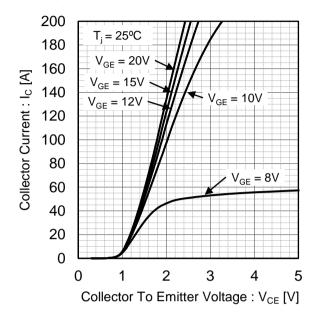


Fig.6 Typical Output Characteristics

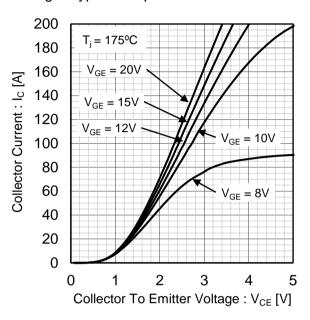


Fig.7 Typical Transfer Characteristics

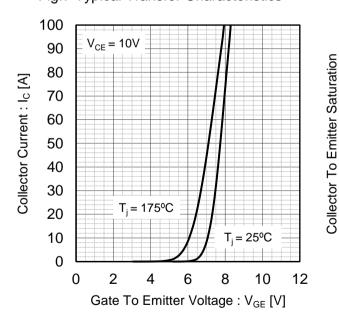
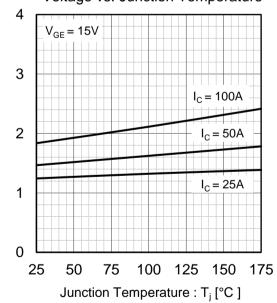


Fig.8 Typical Collector to Emitter Saturation Voltage vs. Junction Temperature



Voltage: V_{CE(sat)} [V]



Fig.9 Typical Collector to Emitter Saturation Voltage vs. Gate to Emitter Voltage 20 $T_i = 25^{\circ}C$ Collector To Emitter Saturation $I_{\rm C} = 100A$ 15 Voltage: V_{CE(sat)} [V] $I_C = 50A$ $I_{\rm C} = 25A$ 10 5 0 5 10 15 20 Gate To Emitter Voltage: VGE [V]

Fig.10 Typical Collector to Emitter Saturation Voltage vs. Gate to Emitter Voltage

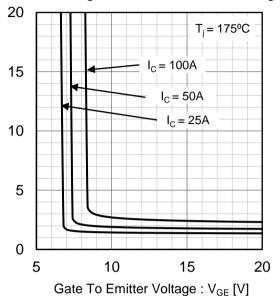
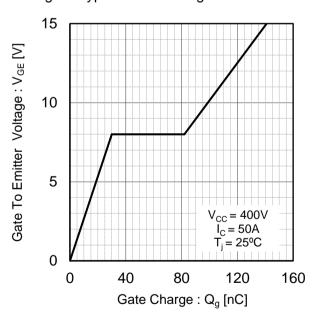


Fig.11 Typical Capacitance vs. Collector to Emitter Voltage 10000 $\mathsf{C}_{\mathsf{ies}}$ 1000 Capacitance [pF] Coes 100 10 f = 1MHz $V_{GE} = 0V$ = 25°C 0.01 0.1 1 10 100 Collector To Emitter Voltage: V_{CE} [V]

Fig.12 Typical Gate Charge



Collector To Emitter Saturation

Voltage: V_{CE(sat)} [V]

Fig.13 Typical Switching Time vs. Collector Current 1000 $t_{d(off)}$ Switching Time [ns] 100 $t_{d(on)}$ 10 V_{CC} = 400V, V_{GE} = 15V, R_G = 10 Ω , T_j = 25°C Inductive load 1 0 20 40 60 80 100

vs. Gate Resistance 1000 t_{d(off)} Switching Time [ns] 100 t_{d(on)} 10 $V_{CC} = 400V, V_{GE} = 15V,$ $I_{C} = 25A, T_{j} = 25^{\circ}C$ Inductive load 1 0 10 20 30 50 Gate Resistance : $R_g [\Omega]$

Fig.14 Typical Switching Time

Fig.15 Typical Switching Energy Losses vs. Collector Current

Collecter Current : I_C [A]

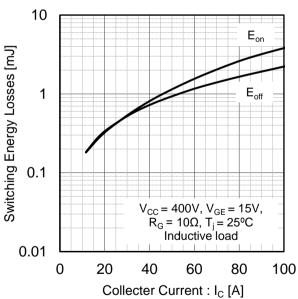


Fig.16 Typical Switching Energy Losses vs. Gate Resistance

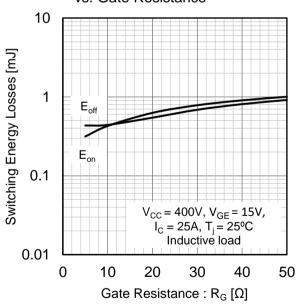


Fig.17 Typical Switching Time vs. Collector Current 1000 $t_{d(off)}$ Switching Time [ns] 100 $t_{d(on)}$ 10 $V_{CC} = 400V, V_{GE} = 15V,$ $R_G = 10\Omega, T_j = 175^{\circ}C$ Inductive load 1 0 20 40 60 80 100 Collecter Current : I_C [A]

vs. Gate Resistance $\begin{array}{c} \text{1000} \\ \hline \\ \frac{\text{ge}}{\text{e}} \\ \text{100} \\ \hline \\ \text{o} \\ \text$

Fig.18 Typical Switching Time

Fig.19 Typical Switching Energy Losses vs. Collector Current 10 Switching Energy Losses [mJ] 1 $\mathsf{E}_{\mathsf{off}}$ E_{on} 0.1 $V_{CC} = 400V, V_{GE} = 15V,$ $R_G = 10\Omega, T_j = 175^{\circ}C$ Inductive load 0.01 0 20 40 60 100 80 Collecter Current : I_C [A]

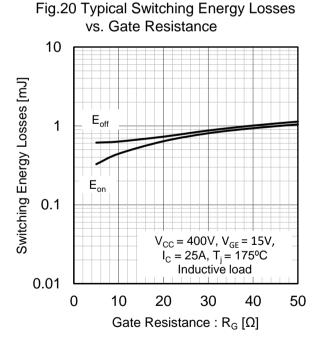


Fig.21 Typical Diode Forward Current vs. Forward Voltage

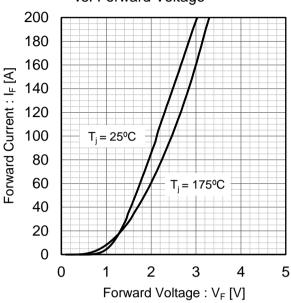


Fig.22 Typical Diode Revese Recovery Time vs. Forward Current

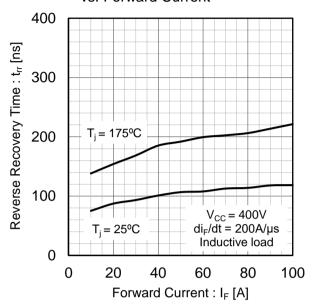


Fig.23 Typical Diode Reverse Recovery Current vs. Forward Current

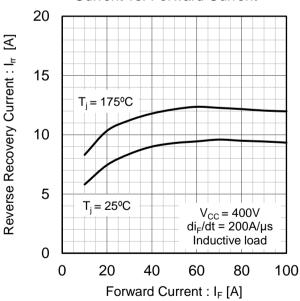


Fig.24 Typical Diode Rrverse Recovery Charge vs. Forward Current

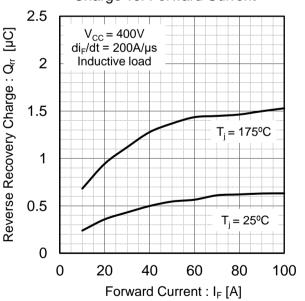


Fig.25 Typical IGBT Transient Thermal Impedance

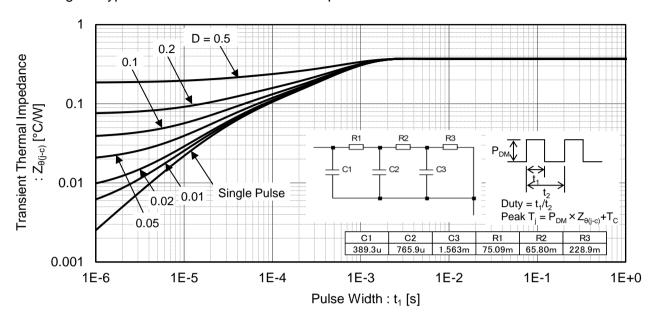
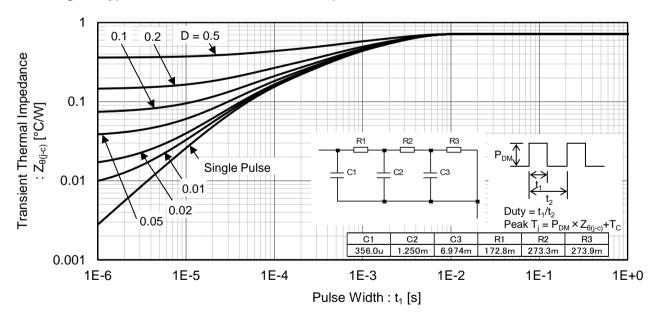


Fig.26 Typical Diode Transient Thermal Impedance



●Inductive Load Switching Circuit and Waveform

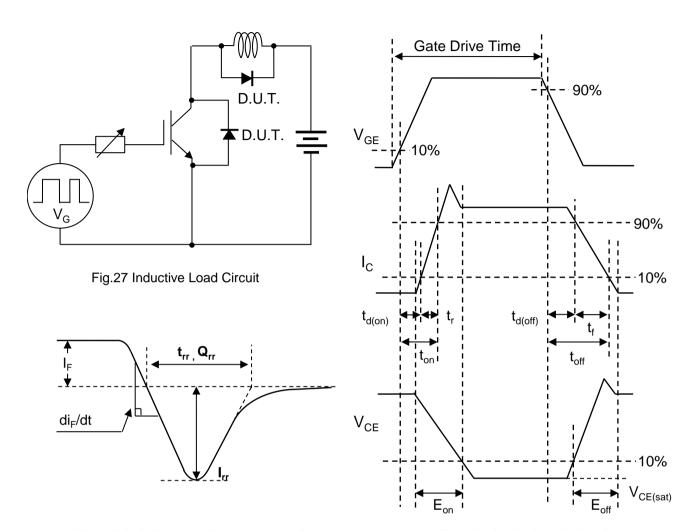


Fig.29 Diode Reverse Recovery Waveform

Fig.28 Inductive Load Waveform

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